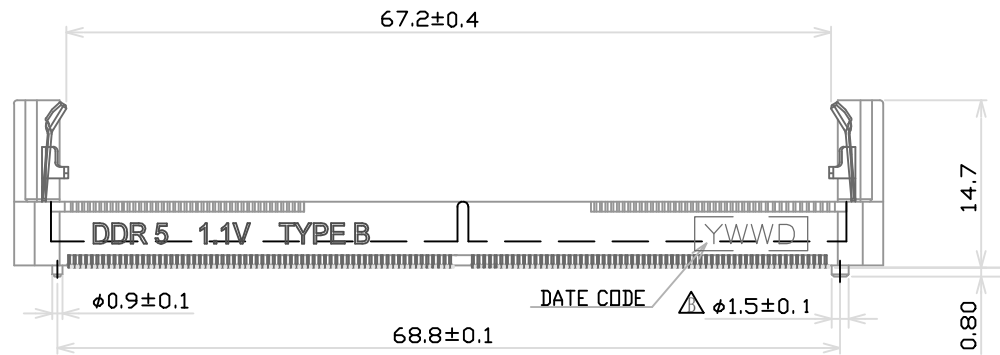
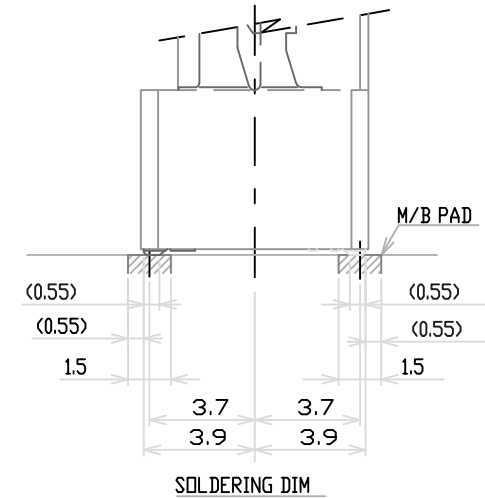
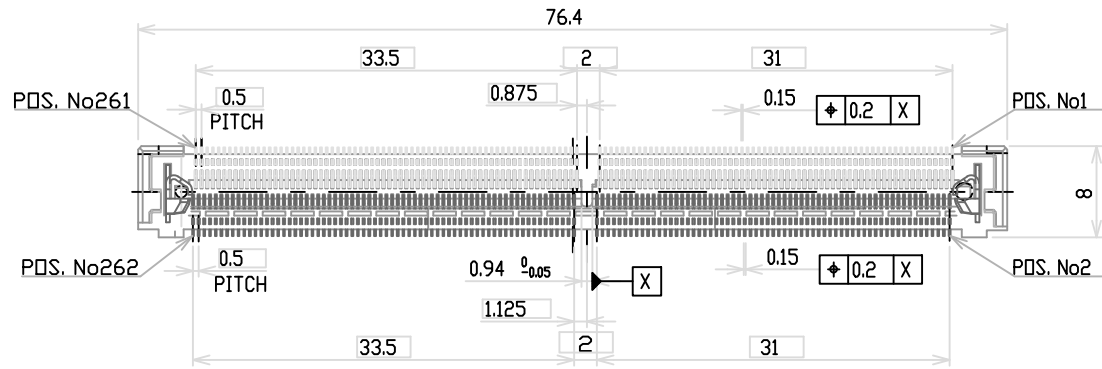


REV.	DESCRIPTION	DATE	DWG.	CHKD
A	PROPOSED	22'01'10	BA'K	HASHIMOTO
B	POST SIZE	22'02'08	BA'K	HASHIMOTO

LEAD FREE

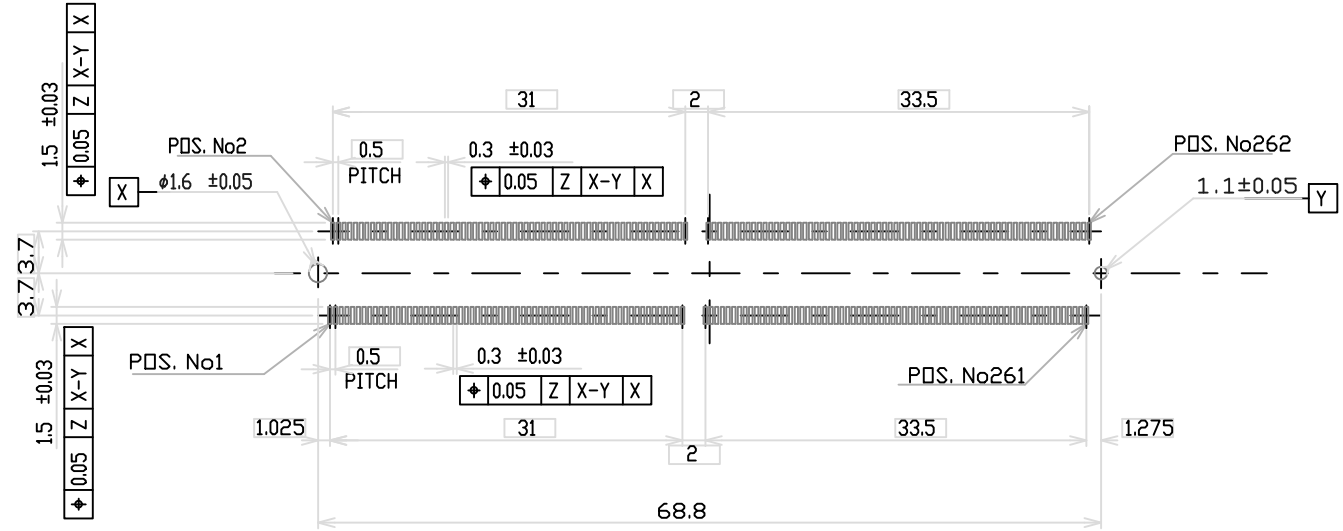
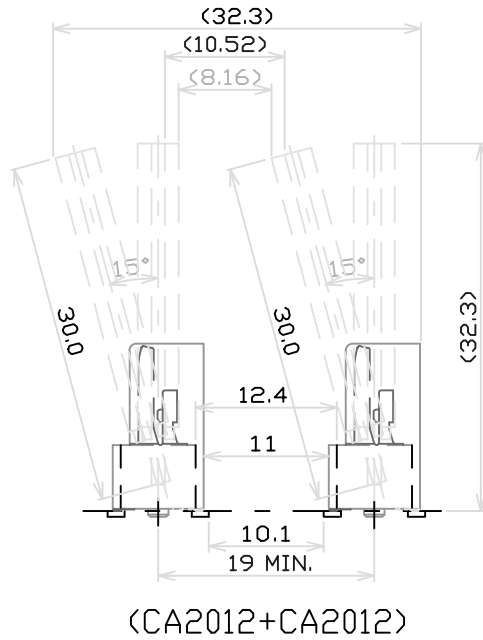


NOTES.

- 材質; ハウジング:LCP樹脂、UL94V-0、色:BLACK
 コンタクト:銅合金
 メタルラッチ:ステンレス
 MATERIAL;HOUSING:LCP,UL 94V-0,COLOR:BLACK
 CONTACT:COPPER ALLOY
 METAL LATCH:SUS
 PEG:PHOS-BRD 80u" TIN PLATING
- メッキ:コンタクト(接点部、半田付け部); 金メッキ表参照、ニッケル下地1.5μmMIN.
 PLATING; CONTACT(CONTACT POINT,SOLDER AREA):
 Au PLATE SEE CHART ,Ni UNDER PLATE 1.5μm MIN.
- コネクタを平坦面に置き、端子半田付け部の浮きは、0.1mm以下
 MUST BE MEASURED FLOATING AMOUNT OF CONTACT TAILS
 FROM DATAM SURFACE IS 0.1mm MAX.

	Au:0.3μ"	1.1V	TYPE B	CA2012-262B01	CA2012-262B31
	FINISH	POWER SUPPLY	KEY TYPE	PART NO. OF CONNECTOR	PART NO. OF PACKAGED PRODUCT (WITH TARY)
MATERIAL	SEE NOTE	NET WEIGHT	***g	COLOR	SEE NOTE
FIN. & TREAT	SEE NOTE	GROSS WEIGHT	***g	GENERAL TOLERANCE	±0.2 ±3°
CUSTOMER	*****	SCALE	2:1	UNIT:mm	
CUSTOMER PART NO.	*****	PART NO.	CA2012-262B**	SIZE	A3
		PROPOSAL NO.	****-**-**-**		
美星鴻科技股份有限公司 MSH TECHNOLOGY INC.			NAME DDR5 S.O DIMM SOCKET VERTICAL TYPE B FOR 262PIN DDR S.O DIMM		
APP: 22,02,08 T.HASHIMOTO	DRW: 22,02,08 T.HASHIMOTO	CHK: 22,02,08 L.BANK	(SHEET 1 OF 4) DATE		

REV.	DESCRIPTION	DATE	DWG.	CHKD
SEE SHEET 1 OF 4				

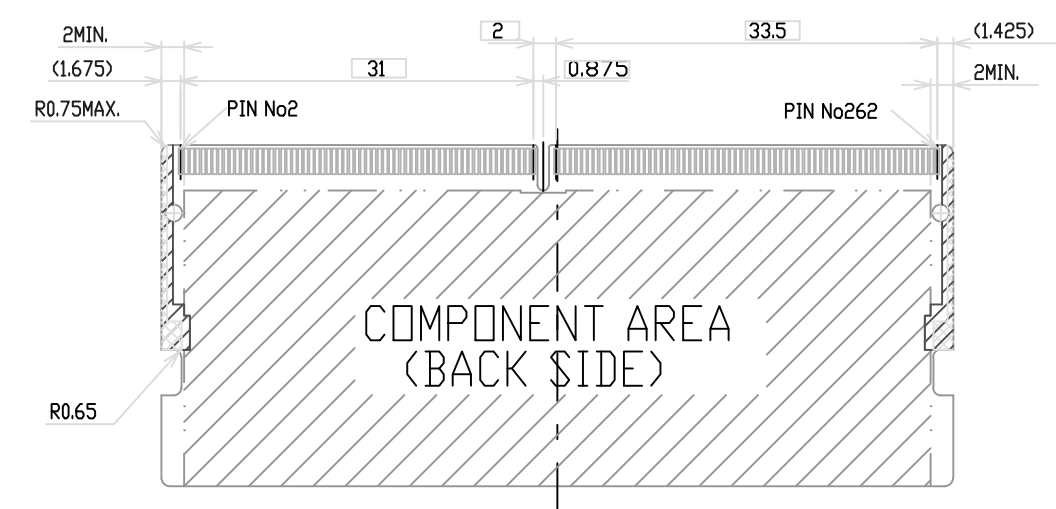
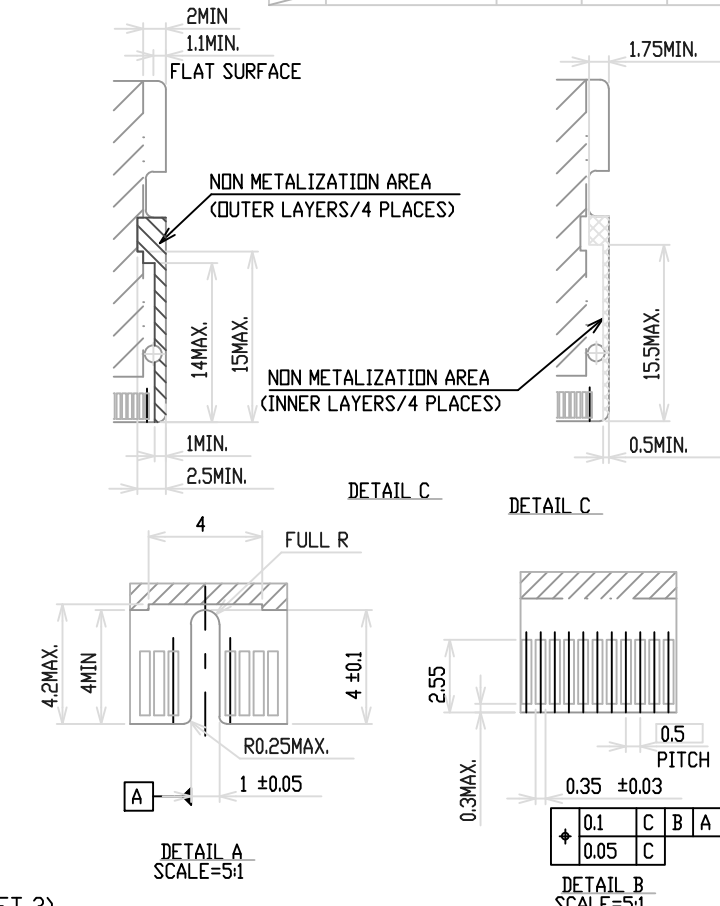
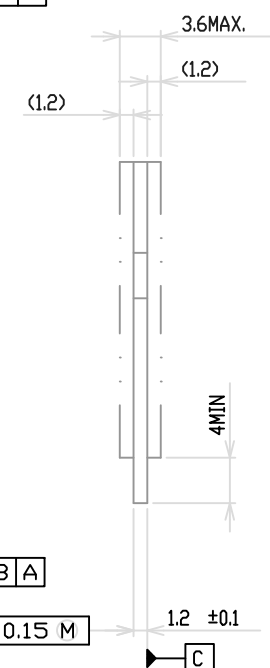
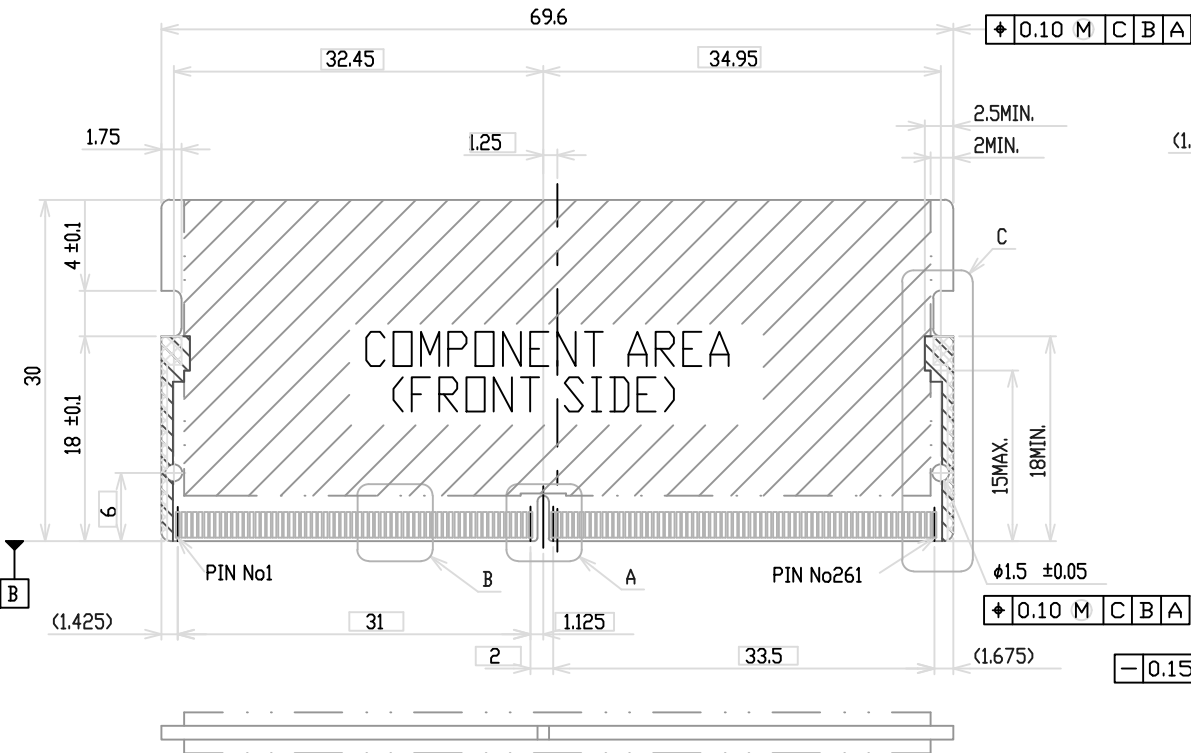


RECOMMENDED MOUNTING
P.C. BOARD PATTERN LAYOUT DIM.

NOTES;

- 1.一般公差±0.15
TOLERANCES ON ALL DIMENSION ±0.15 UNLESS OTHERWISE SPECIFIED.
- 2.PCB面をデータム"Z"とする。
A pcb side be DETAM "Z".

MATERIAL	SEE NOTE	NET WEIGHT	***g	COLOR	SEE NOTE	GENERAL TOLERANCE	±0.15 ±3°	UNIT:mm	
FIN. TREAT	SEE NOTE	GROSS WEIGHT	***g	SCALE	2:1	SIZE	A3		
CUSTOMER	*****	PART NO.	CA2012-262B**			REV.	A		
CUSTOMER PART NO.	*****	PROPOSAL NO.	*****-***-**-**			REV.	*		
美星鴻科技股份有限公司 MSH TECHNOLOGY INC.						(SHEET 2 OF 4)			
APP.	22,02,08	CHKD.	22,02,08	DWG.	22,02,08	NAME			
T.HASHIMOTO		T.HASHIMOTO		L.BANK		DDR5 S.O DIMM SOCKET VERTICAL TYPE B FOR 262PIN DDR S.O DIMM			



注記:(SHEET 3 に適用)
NOTES:(APPLIED TO SHEET 3)
1.一般公差±0.15
TOLERANCES ON ALL DIMENSION ±0.15 UNLESS OTHERWISE SPECIFIED.
2.基板厚寸法は、メッキ厚を含む。
P.C.BOARD THICKNESS APPLIES ACROSS TABS AND INCLUDES PLATING AND/OR METALIZATION.
3.パット部の仕上げ: ニッケル下地メッキ 0.002MIN.厚の上に、金メッキ 0.000756MIN.厚を施す。
FINISH OF PAD: GOLD PLATING 0.00076MIN. OVER Ni PLATING 0.002MIN.

NOTE	FINISH	PART NO.	NAME		NO.
MATERIAL	*****	NET WEIGHT	*****	GENERAL TOLERANCE	UNIT:mm
FIN. TREAT	*****	GROSS WEIGHT	*****	±0.15 ±3°	
CUSTOMER	*****	SCALE	2:1	SIZE	A3
CUSTOMER PART NO.	*****	PART NO.	CA2012-262B**		REV A
	*****	PROPOSAL NO.	*****-****-**-**		REV *
美星鴻科技股份有限公司 MSH TECHNOLOGY INC.			(SHEET 3 OF 4)		
APP: 22,02,08 T.HASHIMOTO	CHKD: 22,02,08 T.HASHIMOTO	DWG: 22,02,08 L.BANK	DDR5 S.O DIMM SOCKET VERTICAL TYPE B FOR 262PIN DDR S.O DIMM		